## What is Claimed:

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- 1 1. A bonding tool for bonding a wire to a substrate, the bonding tool having a body and a working tip coupled to one end of the body, and comprising: 2
- an orifice extending along a longitudinal axis of the body and the working 3 4 tip; and
- a coating disposed over at least a portion of a surface of the orifice. 5
- A capillary bonding tool according to claim 1, wherein the coating 1 extends along an entire length of the orifice. 2
- A capillary bonding tool according to claim 2, wherein the coating 3. is applied to at least a portion of an exterior surface of the working tip. 2
- A capillary bonding tool according to claim 1, wherein the coating 1 is disposed over at least a portion of an exterior surface of the working tip. 2
- A capillary bonding tool according to claim 1, wherein the coating 5. 1 is disposed over an exterior surface of the working tip and the body. 2
- 6. A capillary bonding tool according to claim 1, wherein the coating 1 is a polymer. 2
  - 7. A capillary bonding tool according to claim 1, wherein the coating is at least one of i) a polymer, ii) an Alumina, iii) Si<sub>3</sub>N<sub>4</sub> iv) silica v) a combination of 12% silica and 88% Alumina, and vi) Diamond like Silica (DLC).
- A capillary bonding tool according to claim 1, wherein the coating 1 is a polymer disposed along an interior surface of the orifice and one of i) an Alumina, 2 ii) Si<sub>3</sub>N<sub>4</sub>, iii) silica, iv) a combination of 12% silica and 88% Alumina, and v) Diamond 3 4 like Silica (DLC) disposed along an exterior portion of the orifice.
- 9. A capillary bonding tool according to claim 1, wherein the coating 1 2 has a substantially uniform thickness.
- 10. A capillary bonding tool according to claim 1, wherein the coating 1 has a substantially uniform thickness of up to about 2.0 microns. 2
- 11. A capillary bonding tool according to claim 1, wherein the coating 1 has a substantially uniform thickness of about 0.1 microns. 2

the bonding t	12. A capillary bonding tool according to claim 1, wherein the body of g tool has a substantially cylindrical shape.		
is one of poly	13. yolefin	A capillary bonding tool according to claim 1, wherein the coating e and parylene.	
is formed by	14. vapor j	A capillary bonding tool according to claim 1, wherein the coating phase deposition.	
is formed by	15. one of	A capillary bonding tool according to claim 1, wherein the coating chemical vapor deposition and physical vapor deposition.	
is formed by	16. immer	A capillary bonding tool according to claim 1, wherein the coating sing the bonding tool in a coating material.	
fine wire to a	17. substr	A method of manufacturing a capillary bonding tool for bonding a ate, the method comprising the steps of:	
	formi	ng a cylindrical body;	
	formi	ng a taper at a first end of the body;	
	formi	ng an orifice extending along a longitudinal axis of the body; and	
	coatin	g at least a portion of the orifice with a polymer.	
a substantiall microns.	18. y unifo	The method according to claim 17, wherein the coating step forms orm continuous coating having a thickness of up to about 2.0	
a substantiall	19. y unifo	The method according to claim 17, wherein the coating step forms orm continuous coating having a thickness of at least about 0.1	
comprises the	20. e steps	The method according to claim 17, wherein the coating step of:	
and	formin	ng a precursor monomer at a first temperature and a first pressure;	
and pressure.		ng the coating from the precursor monomer at a second temperature	
	21.	The method according to claim 20, wherein	
	is one of poly is formed by is formed by fine wire to a a substantiall microns. a substantiall micron. comprises the	the bonding tool has  13. is one of polyolefine  14. is formed by vapor  15. is formed by one of  16. is formed by immer  17. fine wire to a substr  formin  formin  coatin  18. a substantially unifor  microns.  19. a substantially unifor  micron.  20. comprises the steps  formin  and  formin  and	

2	the first temperature is about 690°C,		
3	the first pressure is about 0.5 torr,		
4	the second temperature is about 25°C, and		
5	the second pressure is about 0.1 torr.		
1 2 3	22. The method according to claim 20, wherein the precursor monome is formed from a di-Para-Xylyene dimer vaporized at about 150°C and about 1.0 torr followed by a pyrolesis at about 690°C and about 0.5 torr.		
1 2 3	23. The method according to claim 17, wherein the capillary is formed by i) one of direct ceramic dye pressing and ii) injection molding, and machined to a final shape by one of i) grinding and ii) Electro discharge machining.		
1	24. A bonding tool for bonding a wire to a substrate, comprising:		
2	a body portion;		
3	a working tip coupled to one end of the body;		
4	an orifice extending along a longitudinal axis of the body and the working		
5 6 7	a first coating disposed over at least a portion of a surface of the orifice; and		
8 9	a second coating disposed over at least a portion of an exterior surface of the body.		
1 2	25. A capillary bonding tool according to claim 24, wherein the first coating is a polymer and the second coating is other than a polymer.		
1 2	26. A capillary bonding tool according to claim 25, wherein the second coating is one of an alumina and $Si_3N_4$ .		
1 2	27. A method of manufacturing a capillary bonding tool for bonding a fine wire to a substrate, the method comprising the steps of:		
3	forming an orifice extending along a longitudinal axis of the bonding tool		
4	coating at least a portion of the orifice with a polymer; and		

- 5 coating at least a portion of an exterior surface of the bonding tool with a
- 6 non-polymer coating.